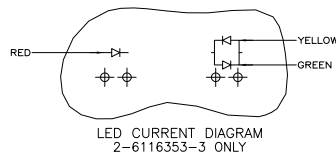
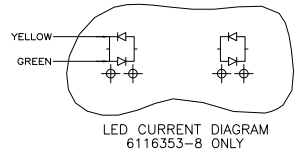
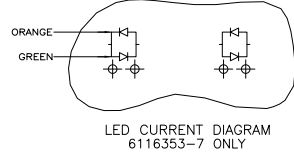
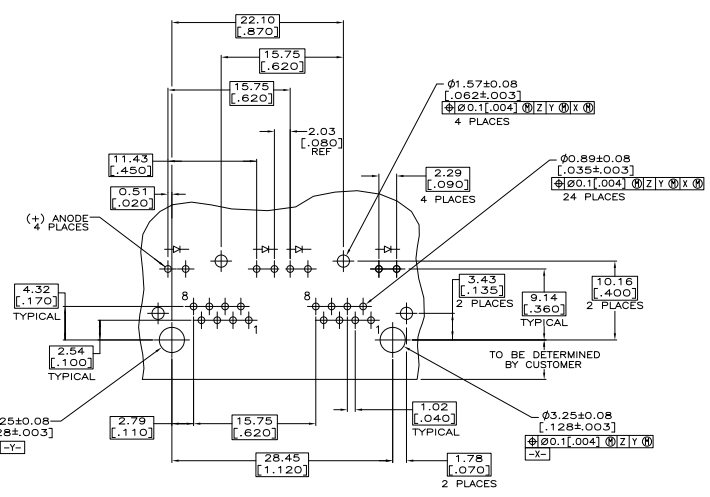
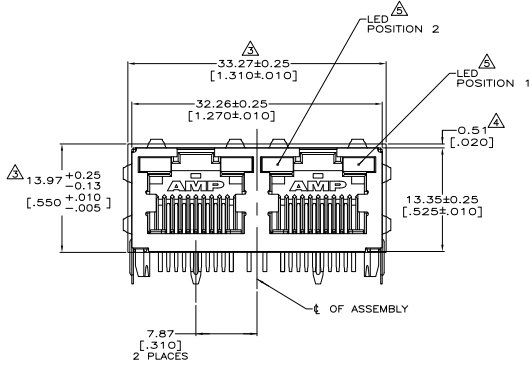
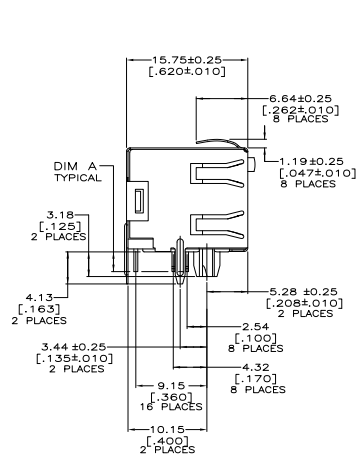
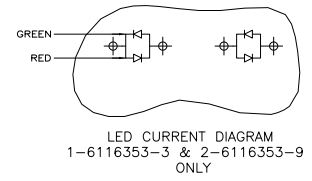


REV	DATE	DESCRIPTION	BY	CHK
AA	00			
C	02-06-2008		JAM	JW
C1	REVISED PER ECO-10-00044		KK	HMR



- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0
 TERMINALS - 0.36[0.014] THICK PHOS BRONZE PLATED WITH 3.81µm[0.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm [0.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[0.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[0.000050] MINIMUM SATIN NICKEL WITH 2.03µm[0.00080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[0.020 x 0.020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm THICK Sn/Cu OVER 2.03 µm THICK Ag OVER 1.02 µm THICK Cu OVER 3.56 µm THICK Ni OVER 1.02 µm THICK Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- SEE TABLE FOR COLOR OF LEADS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- OBsolete PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



SOLDER TAIL LENGTH, DIM A	INDICATOR COLOR FOR EACH HOUSING	POSITION 2	POSITION 1	PART NUMBER
3.55 [1.40]	RED/GREEN	RED/GREEN	RED/GREEN	2-6116353-9
3.05 [1.20]	YELLOW/GREEN	YELLOW/GREEN	YELLOW/GREEN	2-6116353-8
3.05 [1.20]	GREEN	GREEN	GREEN	2-6116353-4
2.54 [1.00]	RED	YELLOW/GREEN	RED/GREEN	2-6116353-3
2.54 [1.00]	RED/GREEN	RED/GREEN	RED/GREEN	1-6116353-3
3.55 [1.40]	YELLOW	GREEN	GREEN	6116353-9
2.54 [1.00]	YELLOW/GREEN	YELLOW/GREEN	YELLOW/GREEN	6116353-8
2.54 [1.00]	ORANGE/GREEN	ORANGE/GREEN	ORANGE/GREEN	6116353-7
2.54 [1.00]	YELLOW	YELLOW	YELLOW	6116353-6
2.54 [1.00]	GREEN	GREEN	GREEN	6116353-5
2.54 [1.00]	GREEN	YELLOW	YELLOW	6116353-4
2.54 [1.00]	YELLOW	-	-	6116353-3
2.54 [1.00]	-	GREEN	GREEN	6116353-2
2.54 [1.00]	YELLOW	YELLOW	YELLOW	6116353-1

SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT

DESIGNED BY	REVIEWED BY	DATE	REV
DATE	DATE	DATE	DATE
DATE	DATE	DATE	DATE
DATE	DATE	DATE	DATE

INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND, WITH LEADS

SEE NOTE 1

CUSTOMER DRAWING